A Trusted Partner for Delivering Telecommunications Solutions



Our devices have become an extension of our daily lives as we are obsessed with sharing and consuming every moment as it happens. Data streaming has exploded with massive amounts of information being shared at the touch of a finger. Communications today is defined in texts, videos, posts, tweets, blogs, calls, etc and the lines between our home and work lives have blurred as our activities converge on our devices. This continuous and compounding demand for more has created huge opportunity and complexity for both the carrier and enterprise markets. They've redefined their relationships with their customers by finding new delivery mechanisms and understanding non-traditional methods to capture their attention, drive usage, secure their data and capture revenue.

UNICOM Engineering has played a key role deploying applications for decades in carrier and enterprise environments. From our early days in computertelephony and ATCA to frames of rackmount servers. With every change we gained knowledge and experience-knowing what it takes to get your products to market. This may mean navigating the strict demands of tier one carriers deploying to telcordia standards, understanding the need for NEBS and DC powered systems to fit traditional telco infrastructure, designing and integrating frame solutions, leveraging specialized cards for DSP and packet processing, obtaining certification to industry and regulatory standards, or supporting mission critical solutions on a global scale. Ultimately, our goal is to design solutions that maximize performance while managing cost in any of these environments with secure, reliable solutions that deliver the ultimate end user experience. Extensive partnerships with leaders like Intel, Dell, Kontron and HP give us access to building blocks and roadmaps while offering you greater flexibility and unmatched deployment options. That's the UNICOM Engineering difference.

Technology Partner Relationships







Hewlett Packard Enterprise

Why Choose UNICOM Engineering?

- Platform Design and Engineering
- Frame Level Design and Integration
- Global Quality Manufacturing Facilities that Maintain ISO and TL 9000 Certifications
- Regulatory and Compliance Expertise
- Complete Integration Services with Built in Controls
- Full Lifecycle Management Control and Reporting
- Custom Branding Expertise
- Global Logistics Capabilities
- Advanced Server and Parts Replacement Coverage
- On-site and Advanced Troubleshooting Services
- Forward and Centralized Stocking Locations Worldwide

UNICOM Engineering Purpose-Built Platforms are ideal for the following types of communications applications:

- Voice & Data Communications
- Mobile & Wireless Communications
- Multi-Media Messaging
- Conferencing & Collaboration
- Load Balancer
- Session Border Controller
- Voice over LTE
- IP Multimedia
- Enterprise Monitoring & Analytics
- Network Monitoring & Management
- Data Collection & Warehousing
- Premium Content & Applications
- Enterprise IP PBX

The following are a few UNICOM Engineering purpose-build appliances well suited for telecom applications.

Appliance Specifications

PLATFORM	E-1800 R5	E-2900 R5	PowerEdge R640	Proliant DL360 G10
Technology Partner	Intel	Intel	Dell EMC	HP
Form Factor	1U Rackmount	2U Rackmount	1U Rackmount	10 Rackmount
Dimensions (H X W X D)	1.7" X 17.25" X 30.25"	3.5" x 17.25" x 31.25"	Chassis depth: 27.75"	1.69" X 17.11" X 27.83"
Processors	Iwo - Intel Xeon Scalable Processors (Skylake Microarchitecture)	Iwo - Intel Xeon Scalable Processors (Skylake Microarchitecture)	(Skylake Microarchitecture)	(Skylake Microarchitecture)
Memory	24 DIMMs, 2 DIMMs / Chan, 6 Memory Chans / Processor, (1,536 GB), DDR4-2666/2400 MT/s	24 DIMMs, 2 DIMMs / Chan, 6 Memory Chans / Processor, (1,536 GB), DDR4-2666/2400 MT/s	24 DDR4 DIMM slots, supports RDIMM /LRDIMM, 1.5 TB max, up to 12 NVDIMM, 192 GB max, supports registered ECC DDR4 DIMMs only, DDR4-2666/2400 MT/s	Up to 3 TB in 24x slots, using 128 GB DIMMs, support for up to 12 NVDIMMs per chassis, DDR4-2666/2400 MT/s
Drive Bays	Four hot swap 3.5" SAS3/SATA3 or Eight hot swap 2.5" SAS3/SATA3/NVMe; Two M.2 SATA3/NVMe	12 hot swap 3.5" SAS3/SATA3/NVMe (2) or 24 hot swap 2.5" SAS3/SATA3/NVMe; Two M.2 SATA3/NVMe	Front drive bays: up to 10 x 2.5" SAS3/SATA3 (HDD/SSD) with up to 8 NVMe SSD max 58 TB or up to 4 x 3.5 SAS3/SATA3 HDD max 40 TB	10 SFF NVMe chassis backplane provides the ability to mix and match SAS/SATA and NVMe within the same chassis along with 8+2 SFF and 4 LFF chassis that supports new uFF and M.2 storage options
RAID Controllers	Two embeded SATA RAID options: RSTe, ESRT2 Available RAID levels: 0,1,5,10; Optional RAID 5 Key for ESRT2. Options VROC Keys for NVMe RAID 0,1,5,10 support.	Two embeded SATA RAID options: RSTe, ESRT2 Available RAID levels: 0,1,5,10; Optional RAID 5 Key for ESRT2. Options VROC Keys for NVMe RAID 0,1,5,10 support.	Two embeded SATA RAID options: RSTe, ESRT2 Available RAID levels: 0,1,5,10; Optional RAID 5 Key for ESRT2. Options VROC Keys for NVMe RAID 0,1,5,10 support.	Two embeded SATA RAID options: RSTe, ESRT2 Available RAID levels: 0,1,5,10; Optional RAID 5 Key for ESRT2. Options VROC Keys for NVMe RAID 0,1,5,10 support.
PCI Slots	Two PCIe slots	Six PCI slots, eight PCI slot w/optional 3rd riser card	Three PCIe slots	Three PCIe slots
Infrastructure Mgmt	Integrated Baseboard Mgmt. Controller, IPMI 2.0 compliant, Remote Mgmt. Module 4 (RMM4)	Integrated Baseboard Mgmt. Controller, IPMI 2.0 compliant, Remote Mgmt. Module 4 (RMM4)	IPMI 2.0 compliant, iDRAC9 with Lifecycle Controller (Express, Enterprise), Quick Sync 2 wireless module optional	HPE iLO Standard with Intelligent Provisioning (embedded), HPE OneView Standard (requires download) HPE iLO Advanced, HPE iLO Advanced Premium Security Edition and HPE OneView Advanced (require licenses)
Media Drives	None	None	Optional DVD-ROM, DVD+RW	Optional DVD-ROM, DVD+RW
Onboard Ethernet Interfaces	Two 10 GbE ports standard - S2600WFT server board only	Two 10 GbE ports standard - S2600WFT server board only	Network daughter card options: 4 x 1 GE or 2 x 10 GE + 2 x 1 GE or 4 x 10 GE or 2 x 25 GE	Embedded 4x 1 GbE plus HPE FlexibleLOM or PCle standup 1 GbE, 10 GbE or 25 GbE adapters
OS Compatibility	Windows 2016/2012 R2, RedHat Linux 7.2/7.1, SuSE Linux 12	Windows 2016/2012 R2, RedHat Linux 7.2/7.1, SuSE Linux 12	Canonical® Ubuntu® LTS, Citrix® XenServer®, Microsoft Windows Server® with Hyper-V, Red Hat® Enterprise Linux, SUSE® Linux Enterprise Server, VMware®ESXi	Windows Server 2012 R2, Windows Server 2016, VMware ESXi 6.0 U3, VMware ESXi 6.5, Red Hat Enterprise Linux (RHEL) 6.9 and 7.3, SUSE Linux Enterprise Server (SLES) 11 SP4 and 12 SP2, ClearOS
Cooling	Six hot swap system fans, one fan per installed power supply module	Six hot swap system fans, one fan per installed power supply module	Hot-plug redundant cooling	Hot-plug redundant standard
Power	Redundant 1100W AC Platinum or 750W DC Gold	Redundant 1300, 1100W AC Platinum or 750W DC Gold	Titanium 750W, Platinum 495W, 750W, 1100W, and 1600W 48VDC 1100W, 380HVDC 1100W, 240HVDC 750W Hot plug power supplies with full redundancy option	Hot-pluggable, redundant 500W AC, 800W AC, and 1600W AC

Learn More: Contact UNICOM Engineering at 800-977-1010 or visit **www.unicomengineering.com**. Our team is ready to help you deliver your solutions faster, better and far more cost effectively.

NOTE: These specifications should be viewed as preliminary and final specifications may vary.

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